

Mounting Procedures

It is important to observe the correct mounting procedures when using Power Semiconductors to ensure effective cooling, good current conduction and reliability. Heatsink preparation is a vital part of the procedure .

(1) ALUMINIUM HEATSINKS^(a) for CAPSULE and FLAT BASE devices:–

Apply a small amount of mounting grease^(b) to the heatsink. Scrub the heatsink area with a wire brush (a 25mm rotary wire cup brush is ideally suited); this action produces a 'slurry'. Clean the mounting surface, or surfaces, in the case of double cooling. Apply a thin film of mounting grease to the semiconductor, and clamp in position observing the clamping procedures below. Warning: a small amount of grease of approximately 0.1mm diameter should be squeezed out of the device/heatsink joint. Excessive use of grease will cause a high voltdrop across the joint and affect heat transfer.

(2) STUD BASE devices:–

Ensure that the device contact surface is clean (a scouring pad, such as 'Scotchbrite', will remove dirt effectively) then apply a thin film of mounting grease to the device ensuring that the threads are clean and free of mounting grease.

Assembly procedures are important:

(1) CAPSULE devices:–

Using 'bar' clamps, either double side or single side, it is important to ensure that all faces are parallel before tightening. The screws should be 'finger' tightened initially, then, using a suitable spanner (wrench) the nuts should be alternately tightened half a turn until the pressure indicating system shows that the required pressure has been achieved.

Using a 'box' clamp, position it over the device ensuring that the pins are correctly located. Position the square steel plate over the central rod, feed bolts (with shakeproof washer) through the clamp whilst holding it firmly in place. Screw the bolts 'finger tight', then alternately, clockwise, half a turn until the box touches the heatsink all the way round.

(2) FLAT (SQUARE) BASE devices:–

Apply mounting grease as for capsules. Ensure that no mounting grease or lubrication is on the fixing screws, then 'finger' tighten them, followed by a torque controlled spanner (wrench) to 1.66 - 2.07 Kgm torque.

(3) STUD BASE devices:–

Ensure that no mounting grease is on the screw thread. Tighten only the hexagonal base using a torque controlled spanner (wrench) to the limit stated for the device.

WESTCODE offer a range of mounting clamps for capsule devices:

<u>Pole Face dia.</u>	<u>Basic Clamp</u>	<u>Type of Clamp</u>
19mm	CMK 450B19M	Box Clamp
25mm	CMK 450x56M	Bar/single/double
25mm	CMK 450B25M	Box Clamp
29.5mm (GTO only)	CMK 550x56M	Bar/single/double
34mm	CMK 1130x76M	Bar/single/double
34mm	CMK 1500B34M	Box Clamp
47mm (GTO only)	CMK 2100x76M	Bar/single/double
47mm	CMK 2140x76M	Bar/single/double
63mm (GTO only)	CMK 2500x116M	Bar/single/double
63mm	CMK 3000x116M	Bar/single/double
75mm (GTO only)	CMK 3500x116M	Bar/single/double
73mm	CMK 4000x116M	Bar/single/double
87mm (GTO only)	CMK 5000x128M	Bar/single/double
87mm	CMK 7000x128M	Bar/single/double

NOTES :

- (a) Recommended machining tolerances over the device mounting area – Flatness 0.03mm, Roughness 1.6µ metres Ra
- (b) Recommended mounting grease – ILEX SCX 13 or PENETROX A-13